

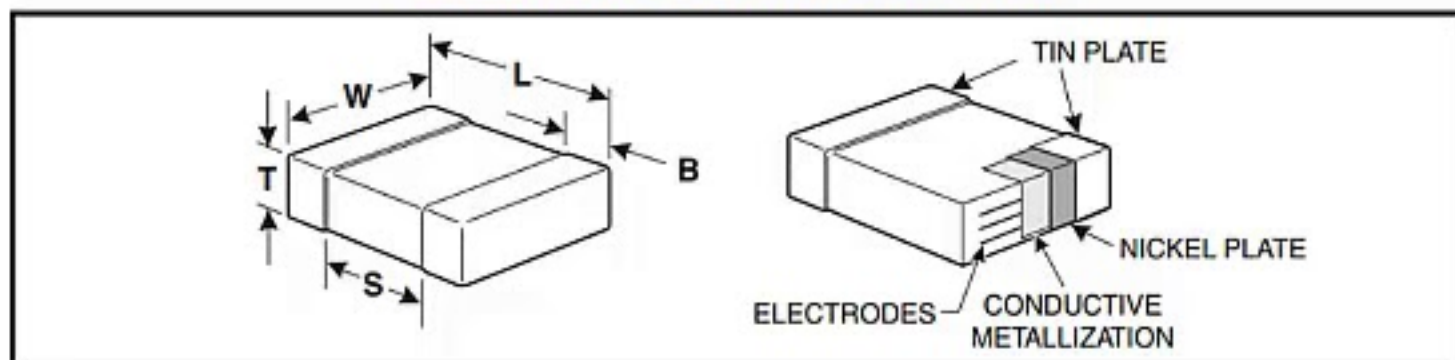
Footprint 생성_Package Symbol 생성(SMD Type)

1608(0603) Size Chip Resistor

Smd1_05x1_08

SMR1608

CAPACITOR OUTLINE DRAWINGS



DIMENSIONS—MILLIMETERS AND (INCHES)

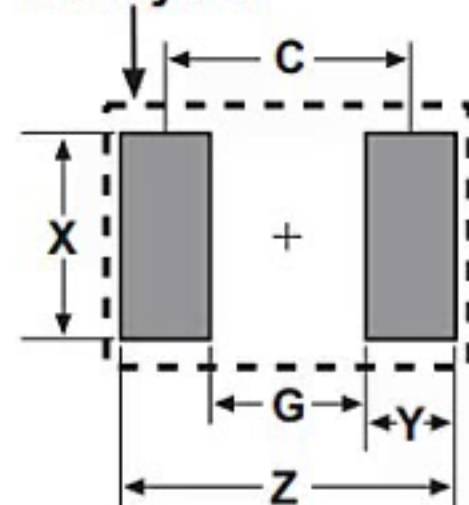
EIA SIZE CODE	METRIC SIZE CODE	L - LENGTH	W - WIDTH	T THICKNESS	B - BANDWIDTH	S SEPARATION minimum	MOUNTING TECHNIQUE
0201*	0603	0.6 (.024) ± .03 (.001)	0.3 ± (.012) ± .03 (.001)	See page 78 for thickness dimensions.	0.15 (.006) ± .05 (.002)	N/A	Solder Reflow
0402*	1005	1.0 (.04) ± .05 (.002)	0.5 (.02) ± .05 (.002)		0.20 (.008) ± .40 (.016)	0.3 (.012)	
0603	1608	1.6 (.063) ± .15 (.006)	0.8 (.032) ± .15 (.006)		0.35 (.014) ± .15 (.006)	0.7 (.028)	Solder Wave + or Solder Reflow
0805*	2012	2.0 (.079) ± .20 (.008)	1.25 (.049) ± .20 (.008)		0.50 (.02) ± .25 (.010)	0.75 (.030)	
1206*	3216	3.2 (.126) ± .20 (.008)	1.6 (.063) ± .20 (.008)		0.50 (.02) ± .25 (.010)	N/A	
1210*	3225	3.2 (.126) ± .20 (.008)	2.5 (.098) ± .20 (.008)		0.50 (.02) ± .25 (.010)	N/A	Solder Reflow
1808	4520	4.5 (.177) ± .30 (.012)	2.0 (.079) ± .20 (.008)		0.60 (.024) ± .35 (.014)	N/A	
1812	4532	4.5 (.177) ± .30 (.012)	3.2 (.126) ± .30 (.012)		0.60 (.024) ± .35 (.014)	N/A	
1825*	4564	4.5 (.177) ± .30 (.012)	6.4 (.252) ± .40 (.016)		0.60 (.024) ± .35 (.014)	N/A	
2220	5650	5.6 (.220) ± .40 (.016)	5.0 (.197) ± .40 (.016)		0.60 (.024) ± .35 (.014)	N/A	
2225	5664	5.6 (.220) ± .40 (.016)	6.3 (.248) ± .40 (.016)		0.60 (.024) ± .35 (.014)	N/A	

(.063)

출처 : KEMET 사의 datasheet INCH

SURFACE MOUNT LAND DIMENSIONS - CERAMIC CHIP CAPACITORS - MM

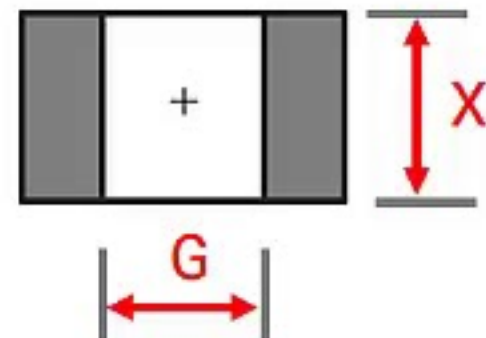
Grid Placement Courtyard



1 Pin Pitch

2 Pad Size

3 Body Size



Dimension	Reflow Solder				
	Z	G	X	Y(ref)	C(ref)
0402	2.14	0.28	0.74	0.93	1.21
0603	2.78	0.68	1.08	1.05	1.73
0805	3.30	0.70	1.60	1.30	2.00
1206	4.50	1.50	2.00	1.50	3.00
1210	4.50	1.50	2.90	1.50	3.00
1812	5.90	2.30	3.70	1.80	4.10
1825	5.90	2.30	6.90	1.80	4.10
2220	7.00	3.30	5.50	1.85	5.15
2225	7.00	3.30	6.80	1.85	5.15